## **CLAIMS**

	we.c	laim:
5055	1.	A method of manufacturing a liquid crystal micro display (lcmd), said method comprising:  creating a hole in a substrate;
್ಷೆಂಶಕ್ತಿ		causing liquid crystal material to flow through said hole; and sealing said hole.
O The first three that the first three	2.	The method of claim 1, further comprising:
n man amus of the state of the		testing said lemd after sealing said hole.
1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	3.	The method of claim 2, further comprising:
#1 ##### ##		separating said lcmd from other cmds after testing said lcmd.
	4.	The method of claim 1, wherein said substrate is a semiconductor substrate.
The state of the s	5.	The method of claim 4, wherein the semiconductor substrate comprises an integrated circuit.
20		
	6.	The method of claim 4, wherein the semiconductor substrate is part of a silicon wafer.
		water.
	7.	The method of claim 1, wherein said substrate comprises glass.
25	8.	The method of claim 1, wherein said hole is sealed using a sealant material
G 37		selected from a group consisting of glue, epoxy, and solder.
17		

5

All the same was the same of t

20

9. A method of manufacturing a first liquid crystal micro display (lcmd) comprising: testing said first lcmd while it is physically connected to a second lcmd; and

separating said first lcmd from said second lcmd after said testing.

- 10. The method of claim 9, wherein said first lcmd comprises a semiconductor substrate having an integrated circuit and a glass substrate having a transparent electrode.
- 11. The method of claim 10, wherein said integrated circuit comprises electrodes.
- 12. The method of claim 11, wherein said testing includes causing a voltage difference between the integrated circuit electrodes and the transparent electrode.
- 13. The method of claim 12, wherein said testing includes determining whether the lcmd produces a uniform image.
- 14. A liquid crystal micro display (lcmd) comprising:
  - a first substrate; and
  - a second substrate having a hole extending through a thickness thereof.
- 15. The lcmd of claim 14, wherein said hole can be used for filling the lcmd with liquid crystal material.
- 25 The lcmd of claim 14, wherein the second substrate is a semiconductor substrate comprising an integrated circuit.
  - 17. The lcmd of claim 14, wherein the second substrate comprises glass.

18. The lcmd of claim 14, wherein said lcmd is physically connected to other lcmds.